

APPARATUS FOR PACKAGING SEMICONDUCTOR DEVICES,
PACKAGED SEMICONDUCTOR COMPONENTS, METHODS
OF MANUFACTURING APPARATUS FOR PACKAGING
SEMICONDUCTOR DEVICES, AND METHODS OF
MANUFACTURING SEMICONDUCTOR COMPONENTS

ABSTRACT OF THE DISCLOSURE

Packaged semiconductor components, apparatus for packaging semiconductor devices, methods of packaging semiconductor devices, and methods of manufacturing apparatus for packaging semiconductor devices. One embodiment of an apparatus for packaging semiconductor devices comprises a first board having a front side, a backside, arrays of die contacts, arrays of first backside terminals electrically coupled to the die contacts, arrays of second backside terminals, and a plurality of individual package areas that have an array of the die contacts, an array of the first backside terminals, and an array of the second backside terminals. The apparatus further includes a second board having a first side laminated to the front side of the first board, a second side, openings through the second board aligned with individual package areas that define die cavities, and arrays of front contacts at the second side electrically coupled to the second backside terminals by interconnects extending through the first board and the second board.

Figure : 1